IEEE EMCS SINGAPORE CHAPTER
IEEE RFID Malaysia Chapter
EMC SOCIETY
APEMC

APEMC
2026 Asia-Pacific International Symposium and Exhibition on Electromagnetic Compatibility

May 4 - 7, 2026, Kuala Lumpur, Malaysia

CALL FOR PAPERS

The 17th Asia-Pacific International Symposium and Exhibition on Electromagnetic Compatibility (APEMC 2026) will be held at **Kuala Lumpur Convention Centre (KLCC)** in **Kuala Lumpur, Malaysia**, from **May 4 to 7, 2026**. The symposium fosters global collaboration, providing a unique opportunity for academia, industry, and regulatory bodies to exchange knowledge and strengthen connections. It also recognizes innovations and pioneering works through the Best Symposium Paper Awards, the Best Student Paper Awards, and other notable contributions. The scope of the symposium involves the entire spectrum of electromagnetic compatibility (EMC), electromagnetic environment, signal integrity and other featured EMC topics in emerging technologies. We warmly invite all prospective authors to submit original papers with the latest research findings and outcomes. We also welcome proposals for focused sessions, industrial forums, workshops, and tutorials.

SYMPOSIUM TOPICS

- EMC Management and Standards
- EMC Measurements and Environment
- Lighting and Protection
- High Power Electromagnetics
- EMC in Renewal Energy and Power Grid
- System-Level EMC and Protection
- Transportation EMC
- Antenna and Propagation
- Aerospace EMC
- IC and Semiconductor EMC
- Signal Integrity and Power Integrity
- Wireless Communication EMC
- Computational Electromagnetics & Multiphysics
- Bio-Medical EM & Wearable Devices EMC
- Nanotechnology and New Materials
- Artificial Intelligence in EMC

More Related Topics are Welcome!

PAPER SUBMISSION

Authors have options for the full-length paper or 1-page abstract submissions.

- Authors can submit a **full-length paper (3-4 pages)** with title, author's affiliation, abstract, methodology, figures and references. The presented full papers will be included in the ***IEEE Digital Xplore***.
- Authors can choose to submit a **1-page abstract** with title, author's affiliation, and crucial findings. The abstract will be published in the conference proceedings, but **NOT** in ***IEEE Digital Xplore***.

A template is available on the APEMC 2026 Symposium website.

The submission must be in electronic format (PDF) via the EDAS system.

IMPORTANT DATES

Proposal for Special Session	October 3, 2025
Proposal for Workshop & Tutorial	November 1, 2025
Paper Submission	**November 21, 2025**
Notification of Acceptance	January 31, 2026
Final Manuscript Submission	February 16, 2026

ADVANCE by LEARN and SHARE

CONTACT US

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LOCATION

Malaysia
Kuala Lumpur
Convention Centre
(KLCC)

Please visit: **https://www.apemc2026.org**

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AWARD COMPETITION

Best Symposium Paper Awards

The Best Paper(s) for APEMC 2026 will be acknowledged to the scientific research in the field of EMC.

Best Student Paper Awards

The full papers entering the Student Paper Prize competition must be predominantly the contribution of the student with him/her being the first author and also the presenter.

Other Awards

APEMC 2026 prepare to recognize outstanding contributions and advancements in latest EMC research via awarding individuals with several other awards, such as Young Scientist Award. Further information will be made available on the symposium website.

ABOUT APEMC 2026

The inaugural APEMC Symposium was started in Singapore in 2008 due to the growing EMC research and development activities in the Asia-Pacific region. After several rotations in different countries, Singapore hosted APEMC the second time in 2012 and then the third time in 2018. In 2026, the IEEE EMC Society Singapore Chapter will organize the symposium again, but the venue will be in Kuala Lumpur, Malaysia. Kuala Lumpur, an hour by flight from Singapore, is a vibrant city in South-East Asia that will offer our delegates a brand-new experience blending modern skyscrapers with cultural attractions, delicious food, and easy accessibility. We are pleased to have the strong support from IEEE RFID Council Malaysia as the Technical Co-Sponsor of the symposium, which signifies the strong tie between Singapore and Malaysia.

ADVANCE by LEARN and SHARE

Please visit: https://www.apemc2026.org

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